

C1206C223MATACTU

Aliases (C1206C223MATAC7800)

SMD Comm X8G HT150C, Ceramic, 0.022 uF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	36 mg	
Shelf Life	78 Weeks	
MSL	1	

0.022 uF

1 kHz 1.0Vrms

45.4545 GOhms

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Т	1.6mm +/-0.20mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

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Т	1.6mm +/-0.20mm
S	1.5mm MIN
В	0.5mm +/-0.25mm
Packaging Specifications	

W	1.6mm +/-0.2mm	Tolerance	20%
Т	1.6mm +/-0.20mm	Voltage DC	250 VDC
S	1.5mm MIN	Dielectric Withstanding Voltage	625 VDC
В	0.5mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
Packaging Quantity	2000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
		Dissipation Factor	O.176 I KHZ I.OVIIIIS
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Specifications

Measurement Condition

Insulation Resistance

Capacitance

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